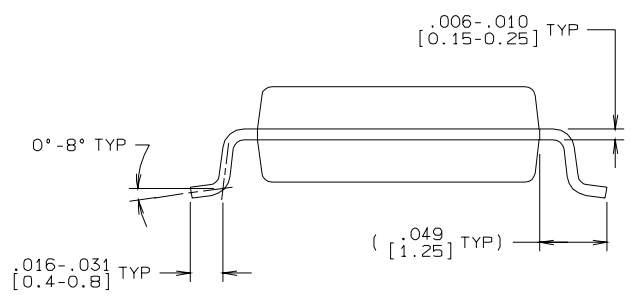
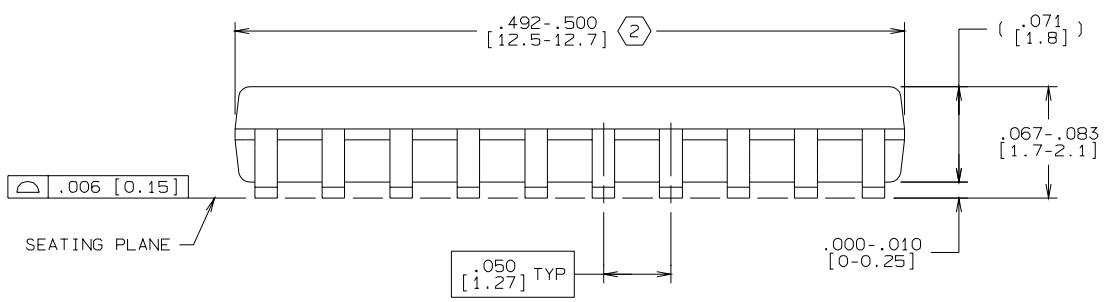
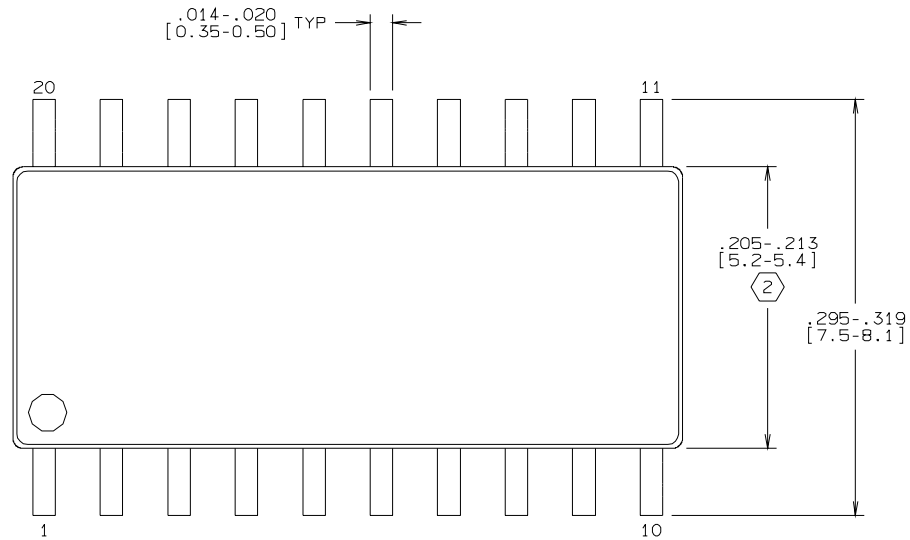


R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	07670	08/01/90	DEG/CC
B	TITLE WAS: MOLDED PACKAGE EIAJ, 300 MIL SOP, 20 LEAD; ADD TYP TO SIDE VIEW DIM'S; REDRAW.	10213	01/04/94	MS/



COTROLLING DIMENSION: MILLIMETER

- NOTES: UNLESS OTHERWISE SPECIFIED
- SOLDER PLATED LEAD FINISH.
 - THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN MARTA SUCHY	01/04/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.		MOLDED SOP, EIAJ TYPE II, 20 LEAD		
ENGR. CHK.				
APPROVAL				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	MKT-M20D	B
DO NOT SCALE DRAWING		SHEET 1 OF 1		